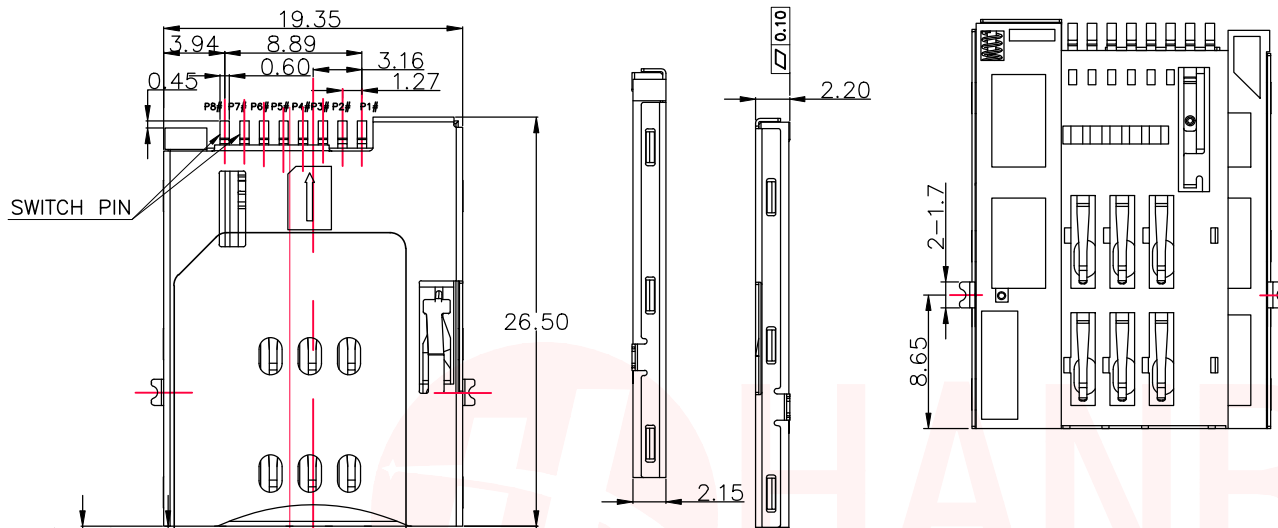




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



NOTES:

1) MATERIAL:

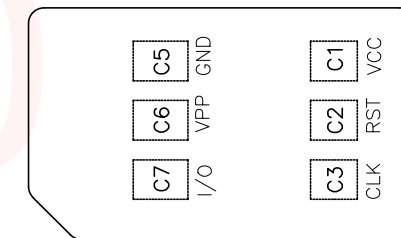
HOUSING: LCP UL 94V-0
 CONTACT: C5210R-H,T=0.15
 SHELL: SUS201,T=0.15
 MYLAR: POLYESTER

2) FINISH :

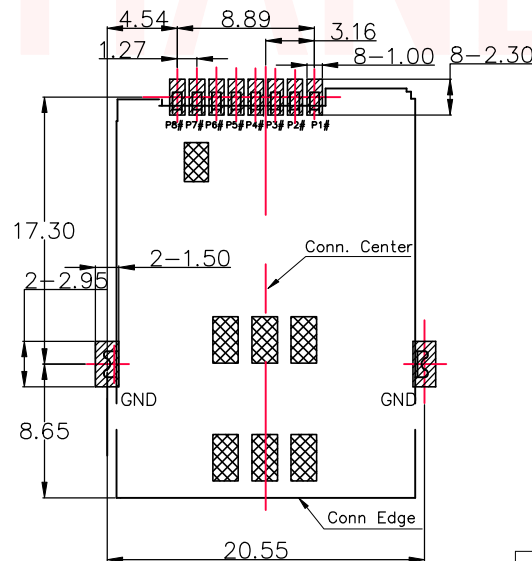
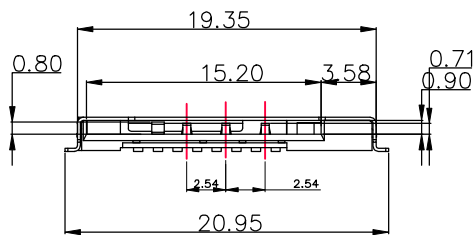
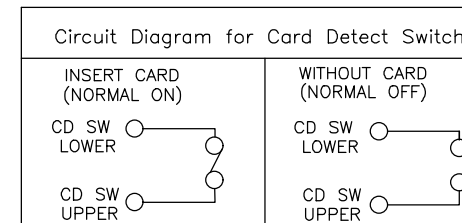
CONTACT: GOLD FLASH PLATED ON CONTACT AREA;
 GOLD FLASH PLATING ON SOLDER TAILS, WITH
 ENTIRE CONTACT UNDERPLATED 30u"Min,NICKEL
 SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
 GOLD FLASH PLATED ON SOLDER TAILS

3) INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10

4) PART NUMBER INFORMATION:



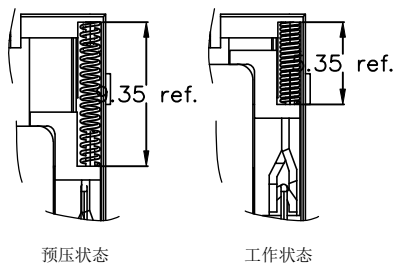
SIM 示意图
 芯片面朝下视图



RECOMMENDED PCB LAYOUT(TOP VIEW)
 GENERAL TOLERANCES:±0.05

SOLDER AREA
 NONE CIRCUIT DIAGRAM AREA

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: X :±0.45 X.X :±0.35 X.XX :±0.25
 ANGLES: X :±2° X.X :±1°

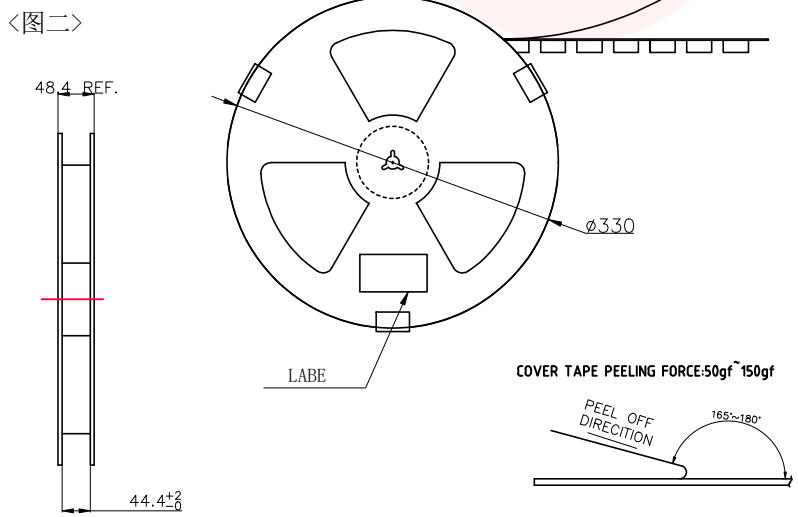
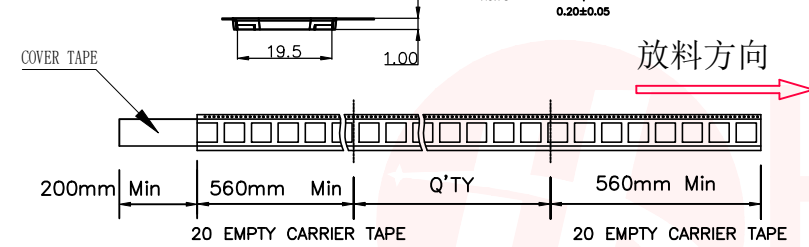
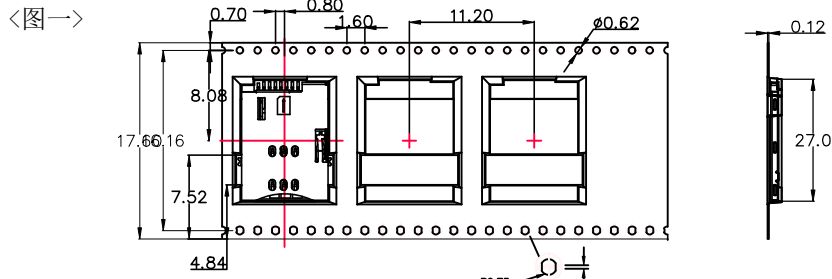


东莞市汉博电子科技有限公司
 DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	PUSH SIM CARD 6+2PIN 2.20H 脚距8.65无柱			
DWN	xiong	PART NO. SIM-1004-P8		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:10F 1	REV: A4
CUSTOMER COPY				



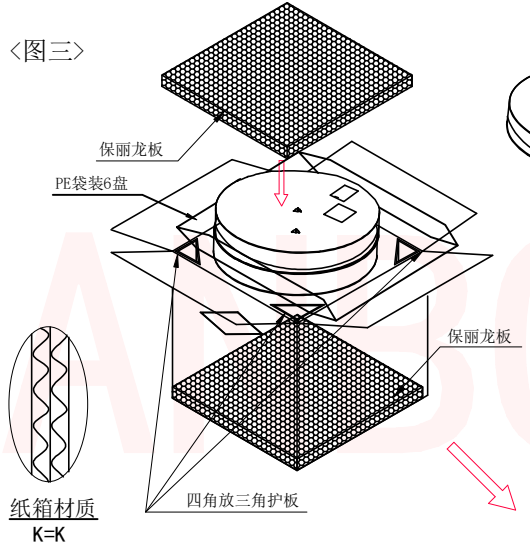
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

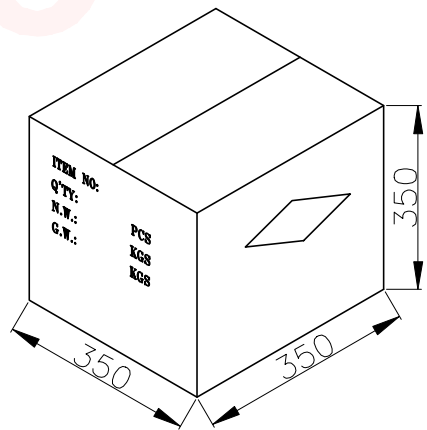
<图三>



纸箱材质 K=K

备注:

- 依<图一>示放置产品于Carrier tape中, 每穴放置1PCS产品, Carrier tape卷绕时, 前端和尾端各需预留20PCS空格.
- Cover tape覆盖Carrier tape前端需超出200mmMIN, 后端需留出300mmMIN, 两端都以美文胶贴固.
- 包装机包好后, 在Reel的个等分点贴上胶带, 以防止REEL张开, 每Reel贴1PCS标签, 如<图二>示
- 包装数量见如<TABLE 1>示
- 包装成箱见如<图三>示
- 箱底放保丽龙板, 再将PE袋(6个Reel盘, 2PCS干燥剂)放入箱内, 四角各放一个三角护板, 最上层再放上保丽龙板.
- 封箱, 在封好的纸箱侧面中间位置贴上出货标签.



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.45	X :±2°
X.X :±0.35	X.X :±1°
X.XX :±0.25	

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